

Nature of traps responsible for failure of MOS devices

V.A. Gritsenko^{*}, P.M. Lenahan^a, Yu.N. Morokov^b, and Yu.N. Novikov

Institute of Semiconductor Physics, Novosibirsk, 630090, Russia

^a The Pennsylvania State University, University Park, Pennsylvania 16802

^b Institute of Computational Technologies, Novosibirsk, 630090, Russia

Abstract

A failure of chips in a huge amount of modern electronic devices such as computers, TV, radio etc is connected as a rule with the undesirable capturing of charge (electrons and holes) by traps in thin insulating film of silicon oxide (SiO_2) in transistors. It leads to a breakdown of transistors or to a destructive change of their characteristics. It is suggested that silicon oxide will be replaced in the next generation of nanoscale devices by silicon oxynitride (SiO_xN_y) [1]. Therefore, it is very important to understand the nature of traps in this material. We discuss this nature using the quantum-chemical simulation.

More than 90 percent of electronic devices are based on silicon. More than 85% of silicon devices are based on Metal-Oxide-Semiconductor (MOS) transistors. The MOS transistor consists of silicon substrate, source, drain, and gate (Fig. 1). Gate is separated from silicon by SiO_2 . The traps in the thin film of SiO_2 can capture electrons or holes from a channel. This is one of the main source of the failure of electronic devices. A key unsolved problem with SiO_2 as a gate dielectric is a hole capture in the Si-Si defects near the Si/ SiO_2 interface and the following device degradation [2].

Silicon oxide, which has been used as the gate dielectric more than thirty years, will be replaced in next generation of nanoscale MOS devices by silicon oxynitride [1]. A gate oxynitride fabrication with high-temperature annealing of thermal SiO_2 in ammonia results in a hole traps removal from the Si/ SiO_2 interface [3] (Fig. 2). However, such oxynitride contains undesirable large density of electron traps. To improve and to control the dielectric properties it is important to understand which structural defects are the dominant traps in oxide and oxynitride. In the present paper we consider, using the quantum-chemical simulation, the nature of such traps in SiO_xN_y and mechanism of creation and removal of traps.

The defects and traps are absent in "ideal" oxynitride containing only the Si-O and Si-N bonds. The oxygen and nitrogen atoms in amorphous silicon oxynitride as in SiO_2 and Si_3N_4 (silicon nitride) are bonded with two and three silicon atoms, respectively [4]. The Si atoms in these materials are bonded with four other atoms (O or N). The traps in SiO_xN_y are related with defects in atomic network.

The main defects, identified in SiO_xN_y , are the next: the silicon-silicon bond ($\equiv\text{Si-Si}\equiv$), the three-fold coordinated silicon atom $\equiv\text{Si}^*$, the two-fold coordinated

nitrogen atom $\equiv\text{Si}_2\text{N}^*$, and the non-bridged oxygen atom $\equiv\text{SiO}^*$. Here "•" marks one unpaired electron. The main defects related with impurities are the hydrogen bonds: $\equiv\text{SiOH}$, $\equiv\text{Si}_2\text{NH}$, and $\equiv\text{SiH}$.

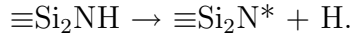
To understand the nature of traps in SiO_xN_y we considered the capturing properties of the main defects in SiO_xN_y . We have studied the electronic structure of the clusters (small fragments of material) in different charge states corresponding to the capture of electrons or holes by traps. The dangling bonds at the cluster surface were saturated with hydrogen atoms. Atomic relaxation of the atoms in the first coordination sphere of defects was considered in the simulation. The calculations were made with the quantum-chemical method MINDO/3 with the parameters used in Refs. [5,6].

We used the $\text{Si}_{18}\text{N}_{17}\text{H}_{35}$ and $\text{Si}_{20}\text{N}_{28}\text{H}_{36}$ clusters for simulation of the Si_3N_4 bulk electronic structure. The clusters with different numbers of oxygen and nitrogen atoms in the second coordination sphere were considered to study the effect of the chemical composition on the capturing properties of the defects in SiO_xN_y . We estimated the energy gain for the electron or hole capture from the bulk of material as the differences between the total energies of the bulk and defect clusters in different charge states.

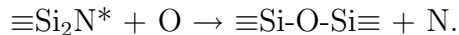
Simulation of the neutral $\equiv\text{Si}_2\text{N}^*$ defect (nitrogen dangling bond) [6] shows that unpaired electron is localized for all considered clusters in a nitrogen $2p_\pi$ orbital, which is oriented normally to the Si_2N plane. This result agrees with the previous theoretical simulation of this defect [7,8] and with the ESR experiments [9,10] for the $\equiv\text{Si}_2\text{N}^*$ defect in Si_3N_4 . The positive energy gain for electron capture by the $\equiv\text{Si}_2\text{N}^*$ defect in Si_3N_4 is about 0.8 eV. It means that the defect can capture an electron. The calculated results show that the $\equiv\text{Si}_2\text{N}^*$ defect in silicon nitride and in oxynitride with a high concentration of nitrogen can capture an electron and cannot capture a hole [6].

The analogue of the $\equiv\text{Si}_2\text{N}^*$ defect in Si_3N_4 is the $\equiv\text{SiO}^*$ defect in SiO_2 . It was shown in Ref. [11] that the $\equiv\text{SiO}^*$ defect is the electron trap in SiO_2 . Our calculations for the $\equiv\text{SiO}^*$ defect in SiO_xN_y and SiO_2 confirm this result. Thus, the obtained results together with experiments show that the $\equiv\text{Si}_2\text{N}^*$ and $\equiv\text{SiO}^*$ defects are the electron traps in gate dielectric.

The $\equiv\text{Si}_2\text{N}^*$ defect creation in SiO_xN_y is related with a breaking of the $\equiv\text{Si}_2\text{N-H}$ bond according to the reaction [10]



We associate the electron traps in oxynitride with these $\equiv\text{Si}_2\text{N}^*$ defects. In order to remove the electron traps from gate oxynitride in silicon devices it is used the reoxidation of oxynitride. The removal of the electron traps at oxynitride reoxidation is explained by replacing of the $=\text{N}^*$ atom with oxygen atom according to the reaction



With this reaction we can understand the chemical nature of one of the key technological step in the MOSFET device fabrication - the electron traps removal at the gate silicon oxynitride reoxidation (Fig. 2).

The calculations have shown that the main extrinsic defects, related with the hydrogen bonds, $\equiv\text{SiOH}$, $\equiv\text{Si}_2\text{NH}$, and $\equiv\text{SiH}$ did not capture electrons and holes.

Our simulation shows that the Si-Si bonds in Si_3N_4 and SiO_2 can be both the electron and hole traps. We have obtained also that the $\equiv\text{Si}^*$ defect in Si_3N_4 and SiO_2 can capture an electron. However, the ESR experiments do not show the existence of this defect in Si_3N_4 and SiO_2 [12].

The recent density functional calculations of the $\equiv\text{Si}^*$ and $\equiv\text{Si}_2\text{N}^*$ defects in silicon nitride [13] confirm that both defects can capture an electron.

Thus, the calculations of the electronic structure of the main intrinsic defects in SiO_xN_y in different charge states support the identification of the $\equiv\text{Si}_2\text{N}^*$ and $\equiv\text{SiO}^*$ defects with the electron traps. The hole traps are related with the Si-Si bonds. This conclusion is in agreement with the results of experiments [14]. It was suggested earlier by Robertson and Powell [15] that the negatively charged nitrogen defect $\equiv\text{Si}_2\text{N}^*$ can be a hole trap. Our results agree with it and show also that the electron localization by neutral defect $\equiv\text{Si}_2\text{N}^*$ leads to the ESR signal disappearance. This effect was experimentally observed earlier [16]. The results of calculations allow to explain the mechanism of creation and removal of the intrinsic defects and to understand the chemistry of the main technological steps in the gate silicon oxynitride fabrication. With these results the nature of the traps responsible for the electron and hole capture in gate oxynitride and so the main source of the silicon devices failure become more clear.

References

* Electronic address: grits@isp.nsc.ru

1. E.P. Gusev, H.C. Lu, E.L. Garfunkel, T. Gustafsson, and M.L. Green, IBM J. Research and Develop. **43** (1999) 1.
2. P.M. Lenahan and P.V. Dressendorfer, J. Appl. Phys. **55** (1984) 3495.
3. V.A. Gritsenko, J.B. Xu, Y.H. Ng, R.W.M. Kwok, and I.H. Wilson, Phys. Rev. Lett. **81** (1998) 1054.
4. I.A. Britov, V.A. Gritsenko, and Yu.N. Romaschenko, Sov. Phys. JETP **62** (1985) 321.
5. V.A. Gritsenko, Yu.N. Morokov, and Yu.N. Novikov, Appl. Surf. Sci. **113/114** (1997) 417.
6. Yu.N. Morokov, V.A. Gritsenko, Yu.N. Novikov, and H. Wong, Microelectronic Engineering **48** (1999) 175.
7. W.L. Warren, J. Robertson, and J. Kanicki, Appl. Phys. Lett. **63** (1993) 2685.
8. L. Martin-Moreno, E. Martinez, J.A. Verges, and F. Yndurain, Phys. Rev. **B35** (1987) 9683.
9. W.L. Warren, P.M. Lenahan, and S.E. Curry, Phys. Rev. Lett. **65** (1990) 207.

10. J.T. Yount and P.M. Lenahan, J. Non-Cryst. Solids **164-166** (1993) 1069.
11. A.H. Edwards and W.B. Fowler, in *Structure and Bonding in Noncrystalline Solids*, G.E. Walrafen and A.G. Revesz, Eds. (Plenum Press, New York and London, 1986) 139-155.
12. V.A. Gritsenko and A. D. Milov, JETP Lett. **64** (1996) 531.
13. G. Pacchioni and D. Erbetta, Phys. Rev. **B61** (2000) 15005.
14. V.A. Gritsenko, I.P. Petrenko, and S.N. Svitashcheva, Appl. Phys. Lett. **72** (1998) 462.
15. J. Robertson and M.J. Powell, Appl. Phys. Lett. **44** (1984) 415.
16. I.A. Chaiyasena, P.M. Lenahan, and G.J. Dunn, Appl. Phys. Lett. **58** (1991) 2141.

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